



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Surface Mount Fuses

Thin Film > 1206 Size > Very Fast-Acting > 466 Series

466 Series 1206 Fast-Acting Fuse



Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
	E10480	.125A - 5A
	29862	.125A - 5A

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	5 sec., Maximum
300%	0.2 sec., Maximum

Additional Information



Datasheet



Resources



Samples

Description

The 466 Series Fast-Acting Surface Mount Fuse (SMF) is a small (1206 size) thin-film device designed for secondary protection of circuits used in space constrained applications such as hand-held portable electronic devices. This series is 100% lead-free and meets the requirements of the RoHS directive. New Halogen-Free 466 Series fuses are available to order using the "HF" suffix. See Part Numbering section for additional information.

Features

- Product is compatible with lead-free solders and higher temperature profiles
- Product is marked on top surface with code to allow amperage rating identification without testing
- Low profile for height sensitive applications
- Flat top surface for pick-and-place operations
- Element-covering material is resistant to industry standard cleaning operations
- Alloy-based element construction provides superior inrush withstand characteristics (I²t) over ceramic or glass-based 1206 chip fuse products
- Lead-free, Halogen-free and RoHS compliant

Applications

Secondary protection for space constrained applications:

- Cell phones
- Battery packs
- Digital cameras
- DVD players
- Hard disk drives

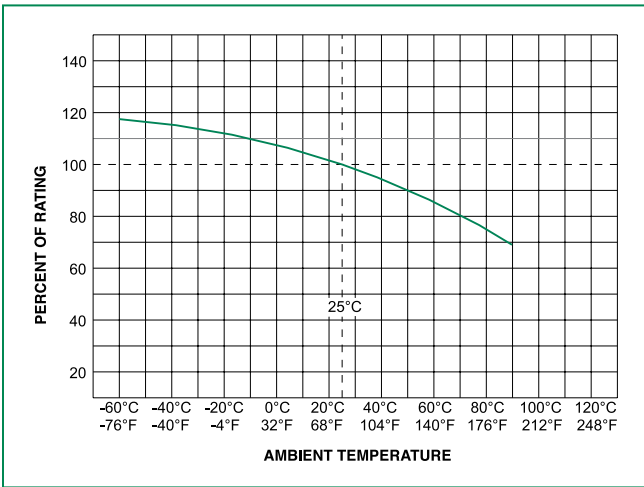
Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Nom Voltage Drop (mV)	Nom Power Dissipation (W)	Agency Approvals	
0.125	.125	125	50A @125 V AC/DC	3.925	0.00064	634.37	0.0793	x	x
0.200	.200	125		1.100	0.00055	254.28	0.0509	x	x
0.250	.250	125		0.691	0.0022	207.01	0.0518	x	x
0.375	.375	125		0.351	0.0045	169.18	0.0634	x	x
0.500	.500	63	50A @63 V AC/DC	0.248	0.0060	158.47	0.0792	x	x
0.750	.750	63		0.106	0.0276	98.65	0.0740	x	x
1.00	001.	63		0.075	0.0423	79.97	0.0800	x	x
1.25	1.25	63		0.057	0.0640	85.71	0.1071	x	x
1.50	01.5	63		0.046	0.1103	82.97	0.1244	x	x
1.75	1.75	63		0.038	0.1835	80.73	0.1413	x	x
2.00	002.	63	50A @32 V AC/DC	0.030	0.2326	78.73	0.1575	x	x
2.50	02.5	32		0.023	0.3516	76.99	0.1925	x	x
3.00	003.	32		0.019	0.5760	75.99	0.2280	x	x
4.00	004.	32		0.014	1.764	74.50	0.2980	x	x
5.00	005.	32		0.011	2.500	73.75	0.3688	x	x

1. Measured at 10% of rated current, 25°C.

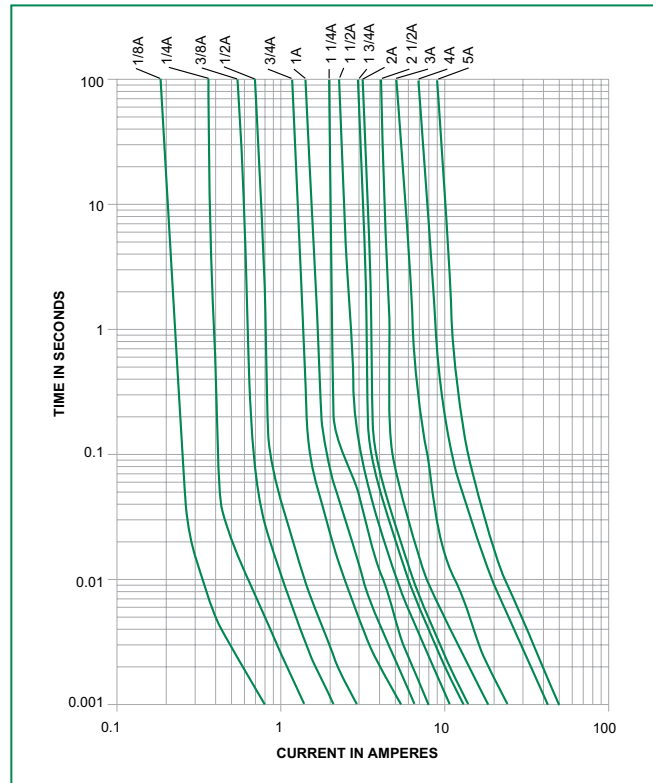
2. Measured at rated voltage.

Temperature Re-rating Curve



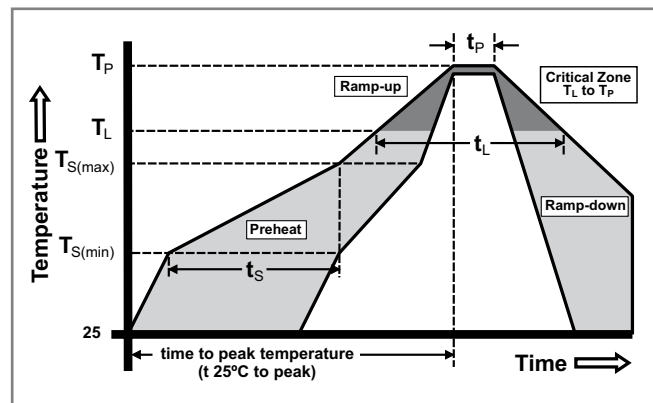
- Note:
1. Re-rating depicted in this curve is in addition to the standard re-rating of 25% for continuous operation.
- Example:
- For continuous operation at 70 degrees celsius, the fuse should be rerated as follows:
 $I = (0.75)(0.80)I_{RAT} = (0.60)I_{RAT}$
2. The temperature derating curve represents the nominal conditions. For questions about temperature derating curve, please consult Littelfuse technical support for assistance.

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_l)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



Wave Soldering	260°C, 10 seconds max.
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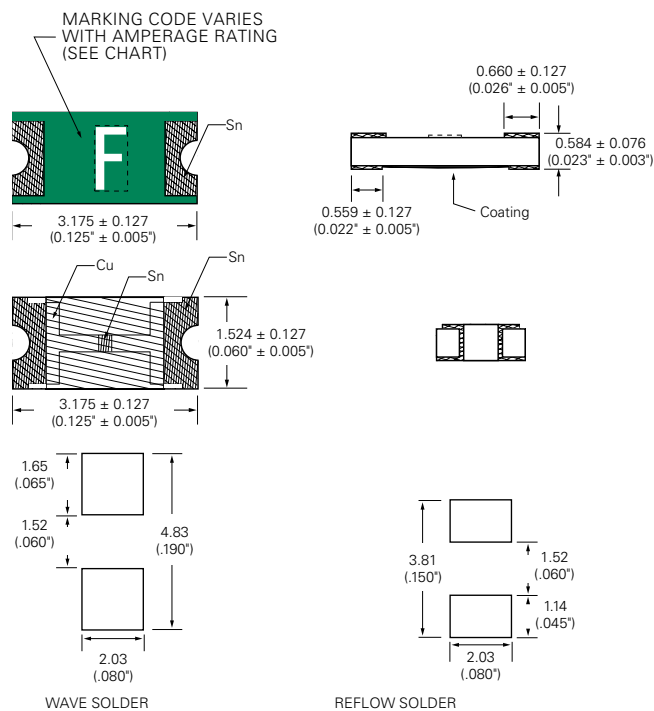
Product Characteristics

Materials	Body: Advanced High Temperature Substrate Terminations: 100% Tin over Nickel over Copper Element Cover Coat: Conformal Coating
Operating Temperature	- 55°C to 90°C. Consult temperature re-rating curve chart.
Thermal Shock	Withstands 5 cycles of -55°C to 125°C
Humidity	MIL-STD-202, Method 103, Condition D
Vibration	MIL-STD-202, Method 201
Insulation Resistance (After Opening)	Greater than 10,000 ohms
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition D

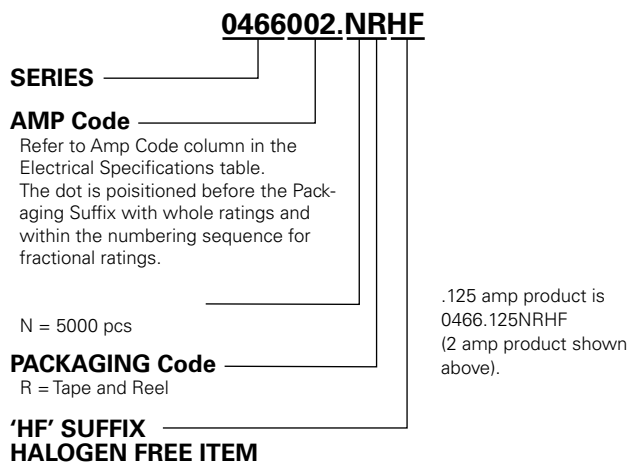
Part Marking System

Amp Code	Marking Code
.125	B
.200	C
.250	D
.375	E
.500	F
.750	G
001.	H
1.25	J
01.5	K
1.75	L
002.	N
02.5	O
003.	P
004.	S
005.	T

Dimensions



Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA-481 Rev. D (IEC 60286, part 3)	5000	NR